

Abstract of the Disclosure

In some embodiments, the invention includes a system having first and second modules; and a circuit board including first and second module connectors to receive the first and second modules, respectively. A first path of conductors extending from the circuit board to the first module connector, to the first module, back to the first module connector, to the circuit board, to the second module connector and to the second module, and wherein the first path in the first module couples to stubs for first and second chips of the first module and the first path in the second module couples to stubs for first and second chips of the first module; and each of the first and second chips include selectable on die terminations.

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